

Thermal Interface Materials

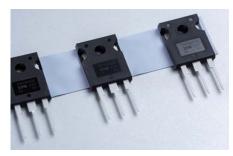
# **TIP Series Thermal Insulators**



The TIP series is Honeywell's latest high-performance thermal conductivity and insulation material. It is made with silicon resin as the matrix, reinforced with glass fiber as the substrate.

#### **TYPICAL APPLICATIONS**

- Automotive electronics
- Power conversion equipment
- Power supply equipment
- Motor controllers
- Speaker amplifier
- Power switch



The TIP series provides low thermal impedance and high insulation for high power and high voltage applications.



**Storage & Use**Shelf Life: 12 months at 23±2°C

#### **Configurations Available**

Sheet form and die-cut parts

#### TIP1500, TIP3500

## HIGH THERMAL CONDUCTIVITY, ELECTRICAL INSULATION

TIP1500 combines 1.5 W/m·K, and TIP3500 combines 3.5 W/m·K thermal conductivity, with superior insulation. TIP1500 and TIP3500 are designed to be soft and conformal, which provides excellent mating surfaces for low-pressure mounting. TIP1500 is offered in 0.19 and 0.23mm thickness. TIP3500 available thicknesses range from 0.25mm to 0.50mm.

#### **FEATURES**

- High thermal performance
- High breakdown voltage
- Good resistance to tears, cut-throughs and punctures
- Single side PSA available for easy assembly

TYPICAL PROPERTIES			
PROPERTY	TIP1500	TIP3500	TEST METHOD
Properties			
Color	Pink	Blue	Visual
Thickness (mm) <sup>2</sup>	0.19, 0.23	0.25-0.50	ASTM D374
Hardness (Shore A)	90	80	ASTM D2240
Specific Gravity	2.21	2.47	ASTM D792
Thermal Properties			
Thermal Conductivity (W/m·K)	1.5	3.5	ASTM D5470
Thermal Impedance °C·in²/W @10psi (typical value)	0.91@0.19mm 0.93@0.23mm	0.23	ASTM D5470
Thermal Impedance °C·in²/W @50psi (typical value)	0.54@0.19mm 061@0.23mm	0.18	ASTM D5470
Electrical Properties			
Dielectric Breakdown Voltage (V)	>6000	>6000	ASTM D149
Dielectric Constant @1MHz	5.50	3.30	ASTM D150
Volume Resistivity (ohm·cm)	1 x 10 <sup>13</sup>	5 x 10 <sup>13</sup>	ASTM D257
Flammability			
Flammability Rating	V-0	V-0	UL94

<sup>&</sup>lt;sup>2</sup> Thickness tolerance: TIP1500: ±0.01mm, (±0.02mm for single side PSA product), TIP3500: ±10%



# **Executive Summary**

Honeywell TIP3500, a softer gap pad with ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces, and maintain excellent performance through reliability testing.

Based on a novel polymer system, this material exhibits excellent reliability. A proprietary filler material provides high thermal conductivity 3.5W/m ·K suitable for high performance devices.

### **Conclusion:**

TIP3500 has excellent thermal stability after different long term reliability tests including, D85(85°C&85%RH) 1000hrs, Thermal Shock 1000cycles and HTB(High Temperature Baking) 125°C 1000hrs.

#### **WORLDWIDE DEVELOPMENT,** MANUFACTURING AND SUPPORT

#### **United States**

Santa Clara, California Sunnyvale, California Spokane, Washington Chandler, Arizona Salt Lake City, Utah Bryan, Texas Houston, Texas Mansfield, Texas Fombell, Pennsylvania Morristown, New Jersey

#### Europe

Seelze, Germany

#### Asia

Shanghai, China Jincheon, Korea Tokyo, Japan Yaita, Japan Chonburi, Thailand Hsinchu, Taiwan Singapore



Research & Development Site Manufacturing Site

Support Site

#### **HONEYWELL TIM ADVANTAGES**

#### Quality

- Industry-leading reliability over device lifetime
- More than twenty years specializing in TIM materials R&D and manufacturing
- Proprietary formulations optimized for the needs of specific applications
- Proven, long-standing supplier with multiple worldwide quality certifications

#### **Customer Focused**

- Serving diverse range of customers
- TIMs offered in both pad and paste formats for ease of application
- Superior global technical support
- Portfolio of other materials, such as thermal spreaders, electrical interconnect and pure metals

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